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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



### Features

- Supports up to 20 watt
- Low Insertion Loss 0.3 dB @ 2.7 GHz
- Low Insertion Loss 0.4 dB @ 10.0 GHz
- High Isolation 55 dB @ 2.7 GHz
- High Isolation 33 dB @ 10.0 GHz
- RoHS\* Compliant

### Description

A broadband, high linearity medium power series shunt switch element in a plastic 1.9 x 1.1 mm DFN package.



(2012)  
Molded Plastic DFN

This device is designed for wireless telecommunication infrastructure and test instrument applications. It is also suited for other applications in 0.1 ~ 10 GHz.

### Electrical Specifications: $T_A = +25^\circ\text{C}$

Parameter	Test Conditions	Min.	Typ.	Max.	Units
Breakdown Voltage	$I_R = 10 \text{ mA}$	200	—	—	V
Junction Capacitance	$V_R = 50 \text{ V}$ , $F = 1 \text{ MHz}$ Shunt Series	—	0.26 0.048	—	pF
Series Resistance	$I_F = 100 \text{ mA}$ , $F = 500 \text{ MHz}$ Shunt Series	—	0.40 0.98	—	Ohms
Lifetime	$I_F = 10 \text{ mA}$ , $I_R = 6 \text{ mA}$ , 10%/90% Shunt Series	—	4300 150	8000 250	ns
Insertion Loss	$I = -50 \text{ mA}^1$ $F = 2.3 \sim 2.7 \text{ GHz}$ $F < 10 \text{ GHz}$	—	0.3 0.6	0.5 0.8	dB
Input Return Loss	$I = -50 \text{ mA}^1$ $F = 2.3 \sim 2.7 \text{ GHz}$ $F < 10 \text{ GHz}$	20 15	25 20	—	dB
Output Return Loss	$I = -50 \text{ mA}^1$ $F = 2.3 \sim 2.7 \text{ GHz}$ $F < 10 \text{ GHz}$	20 15	25 18	—	dB
Isolation	$I = -50 \text{ mA}^1$ $F = 2.3 \sim 2.7 \text{ GHz}$ $F < 10 \text{ GHz}$	45 28	55 35	—	dB

1. Positive current is defined as current going into pin 2.

\* Restrictions on Hazardous Substances, European Union Directive 2011/65/EU.

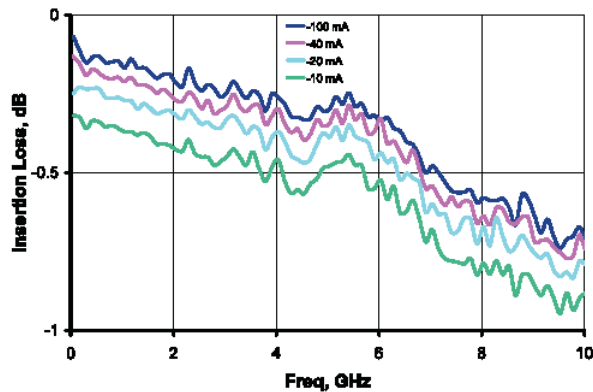
### Absolute Maximum Ratings<sup>3,4</sup>

Parameter	Absolute Maximum
Breakdown Voltage	200 V
Forward Current	100 mA
Input Power	20 W CW
Junction Temperature	+175°C
Storage Temperature	-65°C to +150°C
Solder Temperature	+260°C per JEDEC STD-J-20C

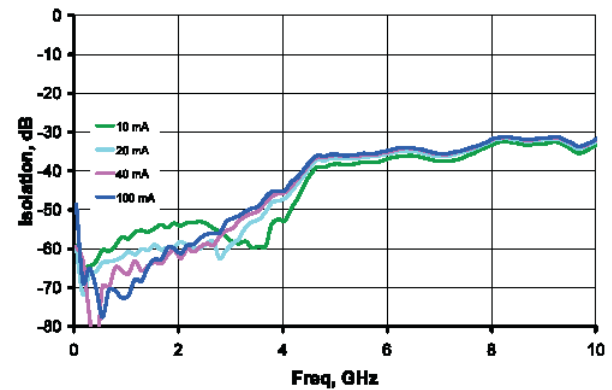
- Exceeding any one or combination of these limits may cause permanent damage to this device.
- MACOM does not recommend sustained operation near these survivability limits.

### Typical RF Performance Curves @ +25°C

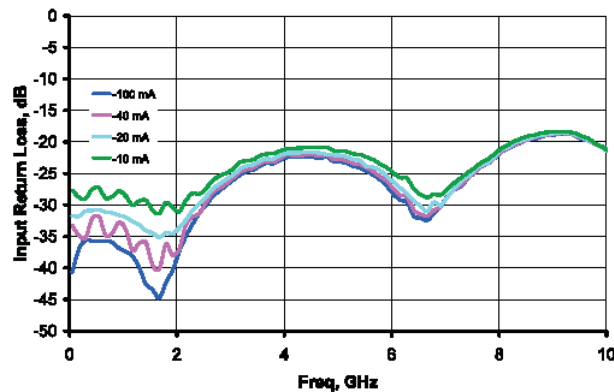
Insertion Loss



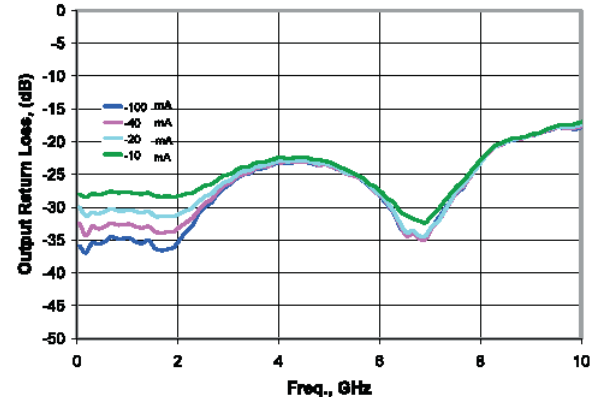
Isolation



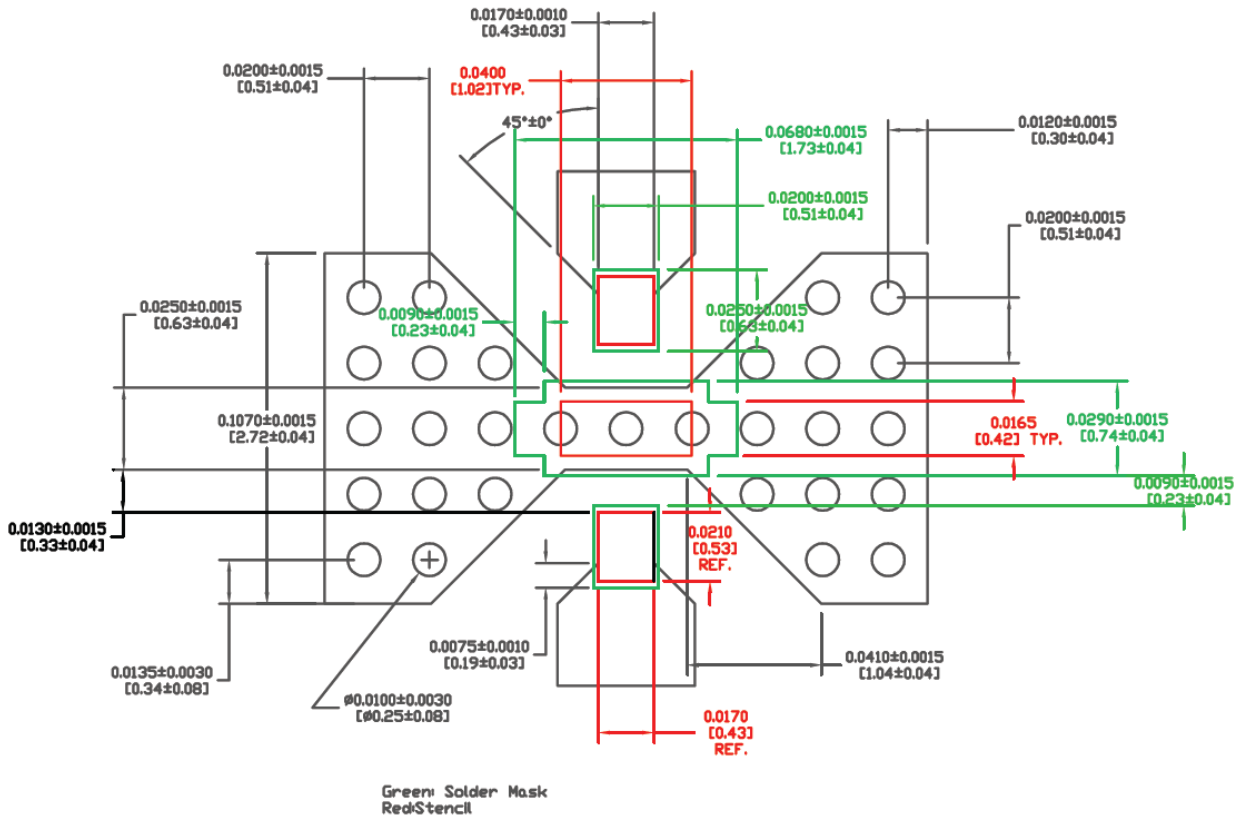
Input Return Loss



Output Return Loss



### Printed Circuit Board Layout



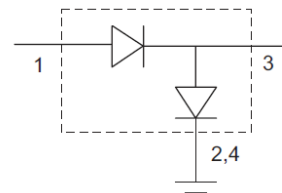
### Assembly

If possible, use copper filled vias underneath pin 3 for better thermals; otherwise, use vias that are plated through, filled and plated over.

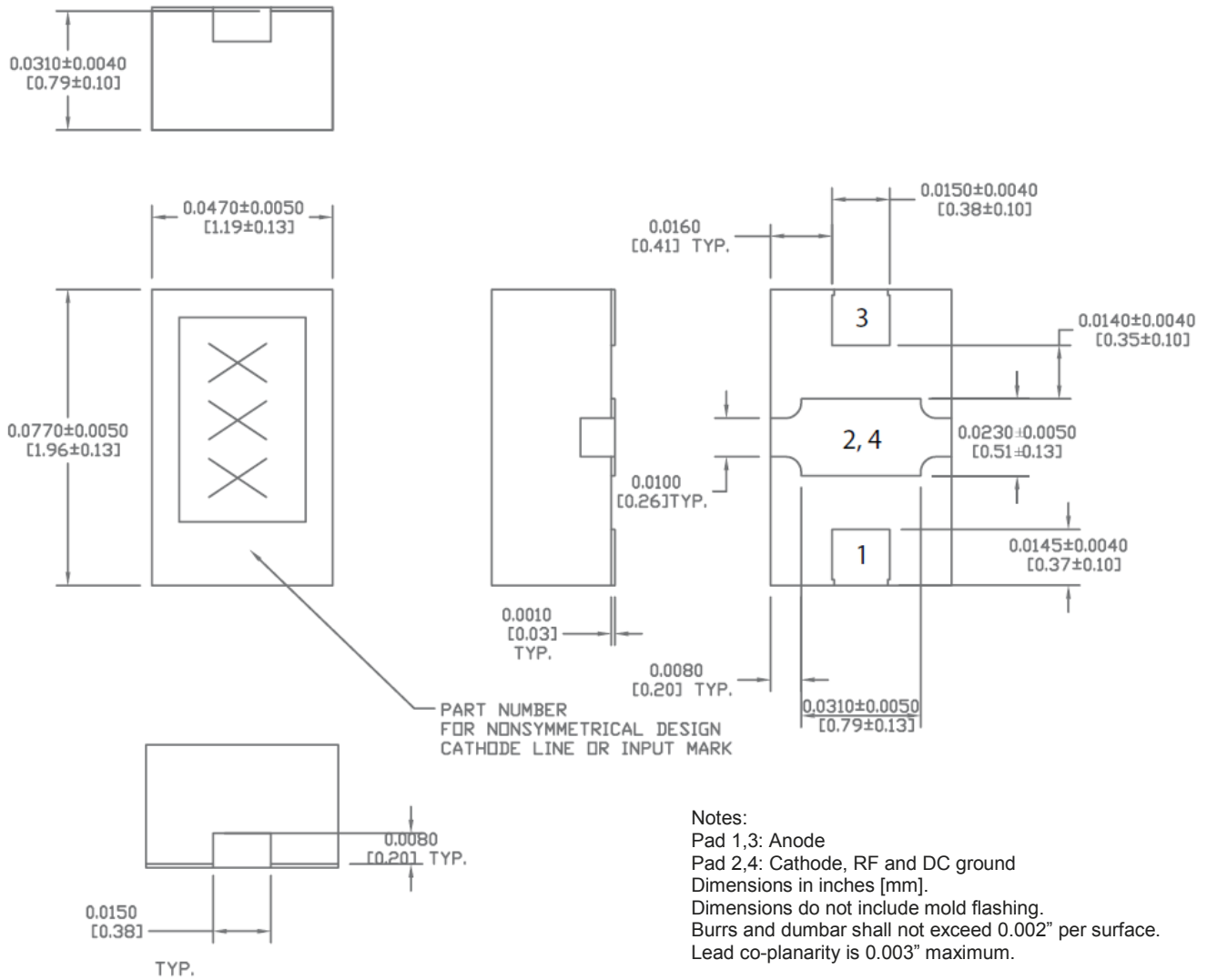
Solder mask should provide a 60  $\mu\text{m}$  clearance between copper pad and solder mask underneath package and 125  $\mu\text{m}$  clearance on outside edges of package. Rounded package pads should have matching rounded solder mask openings.

Use circles or squares for the thermal land stencil such that there is only 50% to 80% solder paste coverage.

### Electrical Schematic



### Outline: 2012 (molded plastic DFN)



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